

DOCKET NO.: CHITTIPEDDI 59-108

PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sailish Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

<p style="text-align: center;">CERTIFICATE OF MAILING</p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450, on <u>5-21-2003</u> (Date)</p> <p><u>Elizabeth Schumacher</u> (Printed or typed name of person signing the certificate)</p> <p><u>Elizabeth Schumacher</u> (Signature of the person signing the certificate)</p>

Sir:

REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111

In response to the Office Action mailed February 25, 2003, please accept the following remarks:

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